



Schedule of Scope to Certificate of Conformity Approved Component – Capability Approval

IECQ Certificate No.: IECQ-C BSI 13.0001

CB Certificate No.: 030/ICA

Schedule Number: IECQ-C BSI 13.0001-S Rev No.: 2 Revision Date: 2015/02/01 Page 1 of 2

Board Types:	Rigid Multilayer (Type 4)	IPC 6012C Class 3*
	Rigid double-sided with plated through holes (Type 2) Rigid single & double-sided with plain holes (Types 1 & 2) Double-Sided boards (Type 2) Single-Sided Boards (Type 1 & 2)	
	Flex-Rigid multilayer with through holes (Type 4)	IPC 6013B Class 3*

*With reduced sampling for structural integrity (micro-section) in accordance with IECQ OD 301

Base Materials: Epoxide Woven Glass (IPC4101, 4202, 4203, BS4584)
Polyimide film/polyester film (IPC 4204)
Polytetrafluorethylene (IPC 4103)

Board Size: 495.30 mm x 419.10 mm single/double and multilayer
261.87 mm x 322.33 mm flex-rigid multilayer

Number of Layers: 32 maximum Rigid multilayer
10 maximum Flex-Rigid multilayer

Conductors: 0.050 mm (photomech) Tolerance -0.01+0.03mm
0.10 mm (photomech) Tolerance -0.02 +0.03 mm

Plated-through Hole Diameter: 0.20 mm Minimum Finished hole size
0.80 mm Minimum Finished hole size

Aspect Ratio: 20 : 1 Maximum single and double sided
16.0:1 Maximum multilayer
2.27 : 1 Maximum flex-rigid multilayer

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Finishes: * Hot Air Solder Levelling
 Immersion Silver
 2.5µm Gold over Copper Edge Contacts
 Liquid Photopolymer Solder Resist
 Legend; UV or Oven Cured
 Solder resist UV cured

Additional: Selective Electroplated Gold (2.5 µm) on Copper
 Selective Electroless Gold (0.05 µm) on Copper
 Silver, Organic Coating
 NemaL1-I

* This finish meets the solderability requirements.

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